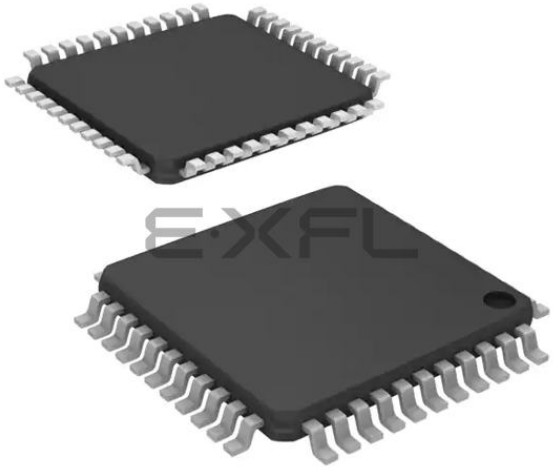

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c44-16i-pt

NOTES:

13.2 USART Asynchronous Mode

In this mode, the USART uses standard nonreturn-to-zero (NRZ) format (one start bit, eight or nine data bits, and one stop bit). The most common data format is 8-bits. An on-chip dedicated 8-bit baud rate generator can be used to derive standard baud rate frequencies from the oscillator. The USART's transmitter and receiver are functionally independent but use the same data format and baud rate. The baud rate generator produces a clock x64 of the bit shift rate. Parity is not supported by the hardware, but can be implemented in software (and stored as the ninth data bit). Asynchronous mode is stopped during SLEEP.

The asynchronous mode is selected by clearing the SYNC bit (TXSTA<4>).

The USART Asynchronous module consists of the following important elements:

- Baud Rate Generator
- Sampling Circuit
- Asynchronous Transmitter
- Asynchronous Receiver

13.2.1 USART ASYNCHRONOUS TRANSMITTER

The USART transmitter block diagram is shown in Figure 13-3. The heart of the transmitter is the transmit shift register (TSR). The shift register obtains its data from the read/write transmit buffer (TXREG). TXREG is loaded with data in software. The TSR is not loaded until the stop bit has been transmitted from the previous load. As soon as the stop bit is transmitted, the TSR is loaded with new data from the TXREG (if available). Once TXREG transfers the data to the TSR (occurs in one T_{CY} at the end of the current BRG cycle), the TXREG is empty and an interrupt bit, TXIF (PIR<1>) is set. This interrupt can be enabled or disabled by the TXIE bit (PIE<1>). TXIF will be set regardless of TXIE and cannot be reset in software. It will reset only when new data is loaded into TXREG. While TXIF indicates the status of the TXREG, the TRMT (TXSTA<1>) bit shows the status of the TSR. TRMT is a read only bit which is set when the TSR is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR is empty.

Note:	The TSR is not mapped in data memory, so it is not available to the user.

Transmission is enabled by setting the TXEN (TXSTA<5>) bit. The actual transmission will not occur until TXREG has been loaded with data and the baud rate generator (BRG) has produced a shift clock (Figure 13-5). The transmission can also be started by first loading TXREG and then setting TXEN. Normally when transmission is first started, the TSR is empty, so a transfer to TXREG will result in an immediate transfer to TSR resulting in an empty TXREG. A back-to-back transfer is thus possible (Figure 13-6). Clearing TXEN during a transmission will cause the transmission to be aborted. This will reset the transmitter and the RA5/TX/CK pin will revert to hi-impedance.

In order to select 9-bit transmission, the TX9 (TXSTA<6>) bit should be set and the ninth bit should be written to TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG. This is because a data write to TXREG can result in an immediate transfer of the data to the TSR (if the TSR is empty).

Steps to follow when setting up an Asynchronous Transmission:

1. Initialize the SPBRG register for the appropriate baud rate.
2. Enable the asynchronous serial port by clearing the SYNC bit and setting the SPEN bit.
3. If interrupts are desired, then set the TXIE bit.
4. If 9-bit transmission is desired, then set the TX9 bit.
5. Load data to the TXREG register.
6. If 9-bit transmission is selected, the ninth bit should be loaded in TX9D.
7. Enable the transmission by setting TXEN (starts transmission).

Writing the transmit data to the TXREG, then enabling the transmit (setting TXEN) allows transmission to start sooner then doing these two events in the opposite order.

Note:	To terminate a transmission, either clear the SPEN bit, or the TXEN bit. This will reset the transmit logic, so that it will be in the proper state when transmit is re-enabled.

FIGURE 13-5: ASYNCHRONOUS MASTER TRANSMISSION

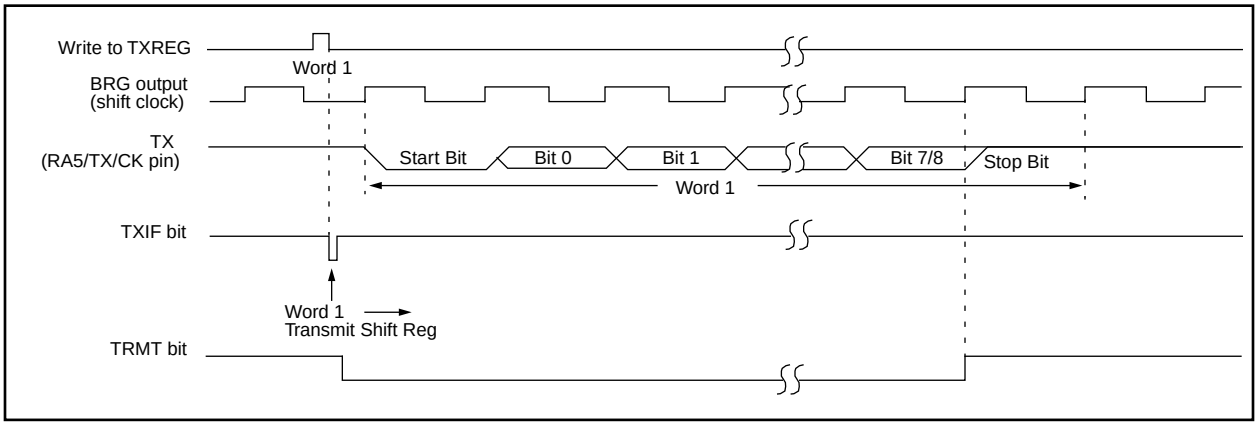
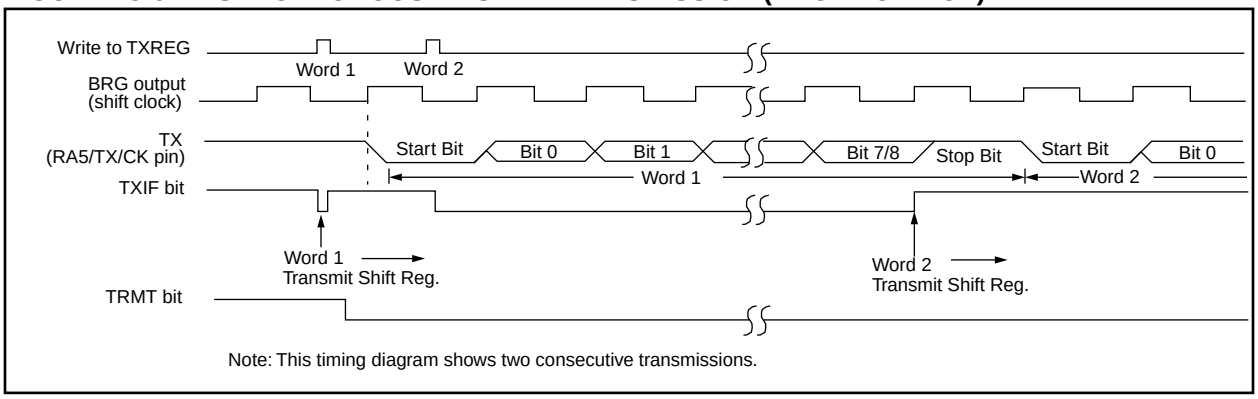


FIGURE 13-6: ASYNCHRONOUS MASTER TRANSMISSION (BACK TO BACK)



Note: This timing diagram shows two consecutive transmissions.

TABLE 13-5: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
16h, Bank 1	PIR	RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TXIF	RCIF	0000 0010	0000 0010
13h, Bank 0	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00u
16h, Bank 0	TXREG	Serial port transmit register								xxxx xxxx	uuuu uuuu
17h, Bank 1	PIE	RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TXIE	RCIE	0000 0000	0000 0000
15h, Bank 0	TXSTA	CSRC	TX9	TXEN	SYNC	—	—	TRMT	TX9D	0000 --1x	0000 --1u
17h, Bank 0	SPBRG	Baud rate generator register								xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as a '0', shaded cells are not used for asynchronous transmission.

Note 1: Other (non power-up) resets include: external reset through $\overline{\text{MCLR}}$ and Watchdog Timer Reset.

14.1 Configuration Bits

The PIC17CXX has up to seven configuration locations (Table 14-1). These locations can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. Any write to a configuration location, regardless of the data, will program that configuration bit. A TABLWT instruction is required to write to program memory locations. The configuration bits can be read by using the TABLRD instructions. Reading any configuration location between FE00h and FE07h will read the low byte of the configuration word (Figure 14-1) into the TABLATL register. The TABLATH register will be FFh. Reading a configuration location between FE08h and FE0Fh will read the high byte of the configuration word into the TABLATL register. The TABLATH register will be FFh.

Addresses FE00h thorough FE0Fh are only in the program memory space for microcontroller and code protected microcontroller modes. A device programmer will be able to read the configuration word in any processor mode. See programming specifications for more detail.

TABLE 14-1: CONFIGURATION LOCATIONS

Bit	Address
FOSC0	FE00h
FOSC1	FE01h
WDTPS0	FE02h
WDTPS1	FE03h
PM0	FE04h
PM1	FE06h
PM2 (1)	FE0Fh (1)

Note 1: This location does not exist on the PIC17C42.

Note:	When programming the desired configuration locations, they must be programmed in ascending order. Starting with address FE00h.

14.2 Oscillator Configurations

14.2.1 OSCILLATOR TYPES

The PIC17CXX can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1:FOSC0) to select one of these four modes:

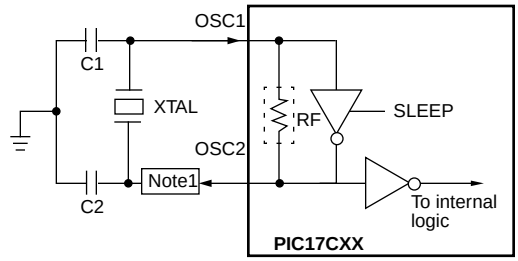
- LF: Low Power Crystal
- XT: Crystal/Resonator
- EC: External Clock Input
- RC: Resistor/Capacitor

14.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT or LF modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 14-2). The PIC17CXX Oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications.

For frequencies above 20 MHz, it is common for the crystal to be an overtone mode crystal. Use of overtone mode crystals require a tank circuit to attenuate the gain at the fundamental frequency. Figure 14-3 shows an example of this.

FIGURE 14-2: CRYSTAL OR CERAMIC RESONATOR OPERATION (XT OR LF OSC CONFIGURATION)



See Table 14-2 and Table 14-3 for recommended values of C1 and C2.

Note 1: A series resistor may be required for AT strip cut crystals.

FIGURE 14-3: CRYSTAL OPERATION, OVERTONE CRYSTALS (XT OSC CONFIGURATION)

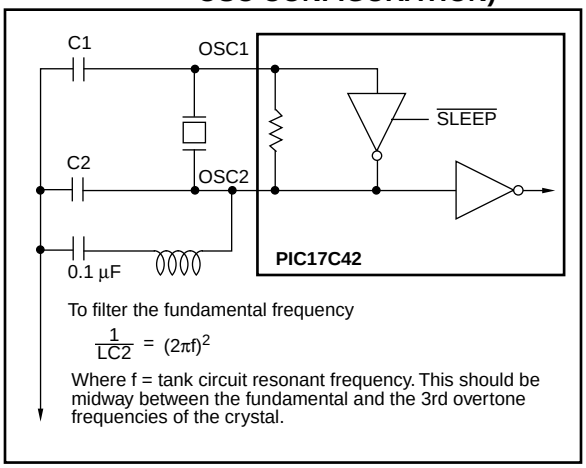


TABLE 14-2: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Oscillator Type	Resonator Frequency	Capacitor Range C1 = C2
LF	455 kHz 2.0 MHz	15 - 68 pF 10 - 33 pF
XT	4.0 MHz 8.0 MHz 16.0 MHz	22 - 68 pF 33 - 100 pF 33 - 100 pF
Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.		
Resonators Used:		
455 kHz	Panasonic EFO-A455K04B	± 0.3%
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%
Resonators used did not have built-in capacitors.		

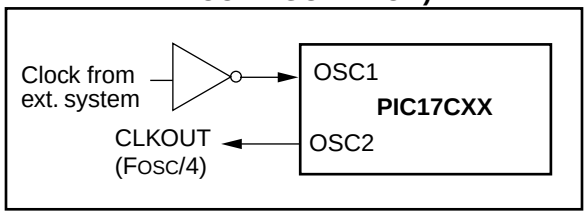
TABLE 14-3: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Freq	C1	C2
LF	32 kHz(1) 1 MHz 2 MHz	100-150 pF 10-33 pF 10-33 pF	100-150 pF 10-33 pF 10-33 pF
XT	2 MHz 4 MHz 8 MHz (2) 16 MHz 25 MHz 32 MHz (3)	47-100 pF 15-68 pF 15-47 pF TBD 15-47 pF 0 (3)	47-100 pF 15-68 pF 15-47 pF TBD 15-47 pF 0 (3)
Higher capacitance increases the stability of the oscillator but also increases the start-up time and the oscillator current. These values are for design guidance only. RS may be required in XT mode to avoid overdriving the crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values for external components. Note 1: For VDD > 4.5V, C1 = C2 ≈ 30 pF is recommended. 2: RS of 330Ω is required for a capacitor combination of 15/15 pF. 3: Only the capacitance of the board was present.			
Crystals Used:			
32.768 kHz	Epson C-001R32.768K-A	± 20 PPM	
1.0 MHz	ECS-10-13-1	± 50 PPM	
2.0 MHz	ECS-20-20-1	± 50 PPM	
4.0 MHz	ECS-40-20-1	± 50 PPM	
8.0 MHz	ECS ECS-80-S-4 ECS-80-18-1	± 50 PPM	
16.0 MHz	ECS-160-20-1	TBD	
25 MHz	CTS CTS25M	± 50 PPM	
32 MHz	CRYSTEK HF-2	± 50 PPM	

14.2.3 EXTERNAL CLOCK OSCILLATOR

In the EC oscillator mode, the OSC1 input can be driven by CMOS drivers. In this mode, the OSC1/CLKIN pin is hi-impedance and the OSC2/CLKOUT pin is the CLKOUT output (4 TOSC).

FIGURE 14-4: EXTERNAL CLOCK INPUT OPERATION (EC OSC CONFIGURATION)



14.4.2 MINIMIZING CURRENT CONSUMPTION

To minimize current consumption, all I/O pins should be either at V_{DD}, or V_{SS}, with no external circuitry drawing current from the I/O pin. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should be at V_{DD} or V_{SS}. The contributions from on-chip pull-ups on PORTB should also be considered, and disabled when possible.

14.5 Code Protection

The code in the program memory can be protected by selecting the microcontroller in code protected mode (PM2:PM0 = '000').

Note:	PM2 does not exist on the PIC17C42. To select code protected microcontroller mode, PM1:PM0 = '00'.

In this mode, instructions that are in the on-chip program memory space, can continue to read or write the program memory. An instruction that is executed outside of the internal program memory range will be inhibited from writing to or reading from program memory.

Note:	Microchip does not recommend code protecting windowed devices.

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

TABLE 15-2: PIC17CXX INSTRUCTION SET (Cont.'d)

Mnemonic, Operands		Description	Cycles	16-bit Opcode				Status Affected	Notes
				MSb			LSb		
TABLWT	**t,i,f**	Table Write	2	1010	11ti	ffff	ffff	None	5
TLRD	**t,f**	Table Latch Read	1	1010	00tx	ffff	ffff	None	
TLWT	**t,f**	Table Latch Write	1	1010	01tx	ffff	ffff	None	
TSTFSZ	**f**	Test f, skip if 0	1 (2)	0011	0011	ffff	ffff	None	6,8
XORWF	**f,d**	Exclusive OR WREG with f	1	0000	110d	ffff	ffff	Z	
BIT-ORIENTED FILE REGISTER OPERATIONS									
BCF	**f,b**	Bit Clear f	1	1000	1bbb	ffff	ffff	None	
BSF	**f,b**	Bit Set f	1	1000	0bbb	ffff	ffff	None	
BTFSC	**f,b**	Bit test, skip if clear	1 (2)	1001	1bbb	ffff	ffff	None	6,8
BTFSS	**f,b**	Bit test, skip if set	1 (2)	1001	0bbb	ffff	ffff	None	6,8
BTG	**f,b**	Bit Toggle f	1	0011	1bbb	ffff	ffff	None	
LITERAL AND CONTROL OPERATIONS									
ADDLW	**k**	ADD literal to WREG	1	1011	0001	kkkk	kkkk	OV,C,DC,Z	
ANDLW	**k**	AND literal with WREG	1	1011	0101	kkkk	kkkk	Z	
CALL	**k**	Subroutine Call	2	111k	kkkk	kkkk	kkkk	None	7
CLRWDT	**—**	Clear Watchdog Timer	1	0000	0000	0000	0100	$\overline{TO}$,$\overline{PD}$	
GOTO	**k**	Unconditional Branch	2	110k	kkkk	kkkk	kkkk	None	7
IORLW	**k**	Inclusive OR literal with WREG	1	1011	0011	kkkk	kkkk	Z	
LCALL	**k**	Long Call	2	1011	0111	kkkk	kkkk	None	4,7
MOVLB	**k**	Move literal to low nibble in BSR	1	1011	1000	uuuu	kkkk	None	
MOVLR	**k**	Move literal to high nibble in BSR	1	1011	101x	kkkk	uuuu	None	9
MOVLW	**k**	Move literal to WREG	1	1011	0000	kkkk	kkkk	None	
MULLW	**k**	Multiply literal with WREG	1	1011	1100	kkkk	kkkk	None	9
RETFIE	**—**	Return from interrupt (and enable interrupts)	2	0000	0000	0000	0101	GLINTD	7
RETLW	**k**	Return literal to WREG	2	1011	0110	kkkk	kkkk	None	7
RETURN	**—**	Return from subroutine	2	0000	0000	0000	0010	None	7
SLEEP	**—**	Enter SLEEP Mode	1	0000	0000	0000	0011	$\overline{TO}$, $\overline{PD}$	
SUBLW	**k**	Subtract WREG from literal	1	1011	0010	kkkk	kkkk	OV,C,DC,Z	
XORLW	**k**	Exclusive OR literal with WREG	1	1011	0100	kkkk	kkkk	Z	

Legend: Refer to Table 15-1 for opcode field descriptions.

Note 1: 2's Complement method.

2: Unsigned arithmetic.

3: If s = '1', only the file is affected: If s = '0', both the WREG register and the file are affected; If only the Working register (WREG) is required to be affected, then f = WREG must be specified.

4: During an LCALL, the contents of PCLATH are loaded into the MSB of the PC and kkkk kkkk is loaded into the LSB of the PC (PCL)

5: Multiple cycle instruction for EPROM programming when table pointer selects internal EPROM. The instruction is terminated by an interrupt event. When writing to external program memory, it is a two-cycle instruction.

6: Two-cycle instruction when condition is true, else single cycle instruction.

7: Two-cycle instruction except for TABLRD to PCL (program counter low byte) in which case it takes 3 cycles.

8: A "skip" means that instruction fetched during execution of current instruction is not executed, instead an NOP is executed.

9: These instructions are not available on the PIC17C42.

IORWF **Inclusive OR WREG with f**

Syntax: [*label*] IORWF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (WREG) .OR. (f) → (dest)

Status Affected: Z

Encoding:

0000	100d	ffff	ffff

Description: Inclusive OR WREG with register 'f'. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example:
```
IORWF  RESULT, 0
```
Before Instruction
RESULT = 0x13
WREG = 0x91

After Instruction
RESULT = 0x13
WREG = 0x93

LCALL **Long Call**

Syntax: [*label*] LCALL k

Operands: $0 \le k \le 255$

Operation: PC + 1 → TOS;
k → PCL, (PCLATH) → PCH

Status Affected: None

Encoding:

1011	0111	kkkk	kkkk

Description: LCALL allows an unconditional subroutine call to anywhere within the 64k program memory space.

First, the return address (PC + 1) is pushed onto the stack. A 16-bit destination address is then loaded into the program counter. The lower 8-bits of the destination address is embedded in the instruction. The upper 8-bits of PC is loaded from PC high holding latch, PCLATH.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Execute	Write register PCL
Forced NOP	NOP	Execute	NOP

Example:
```
MOVLW  HIGH(SUBROUTINE)
MOVPF  WREG, PCLATH
LCALL  LOW(SUBROUTINE)
```
Before Instruction
SUBROUTINE = 16-bit Address
PC = ?

After Instruction
PC = Address (SUBROUTINE)

Applicable Devices	42	R42	42A	43	R43	44

17.1 DC CHARACTERISTICS: PIC17C42-16 (Commercial, Industrial) PIC17C42-25 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	4.5	–	5.5	V	
D002	VDR	RAM Data Retention Voltage (Note 1)	1.5 *	–	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure internal Power-on Reset signal	–	VSS	–	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure internal Power-on Reset signal	0.060*	–	–	mV/ms	See section on Power-on Reset for details
D010	IDD	Supply Current (Note 2)	–	3	6	mA	FOSC = 4 MHz (Note 4)
D011			–	6	12 *	mA	FOSC = 8 MHz
D012			–	11	24 *	mA	FOSC = 16 MHz
D013			–	19	38	mA	FOSC = 25 MHz
D014			–	95	150	µA	FOSC = 32 kHz WDT enabled (EC osc configuration)
D020	IPD	Power-down Current (Note 3)	–	10	40	µA	VDD = 5.5V, WDT enabled
D021			–	< 1	5	µA	VDD = 5.5V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD or VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.
Current consumed from the oscillator and I/O's driving external capacitive or resistive loads need to be considered.
For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: VDD / (2 • R).
For capacitive loads, The current can be estimated (for an individual I/O pin) as (CL • VDD) • f
CL = Total capacitive load on the I/O pin; f = average frequency on the I/O pin switches.
The capacitive currents are most significant when the device is configured for external execution (includes extended microcontroller mode).

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula IR = VDD/2Rext (mA) with Rext in kOhm.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 19-11: MEMORY INTERFACE WRITE TIMING (NOT SUPPORTED IN PIC17LC4X DEVICES)

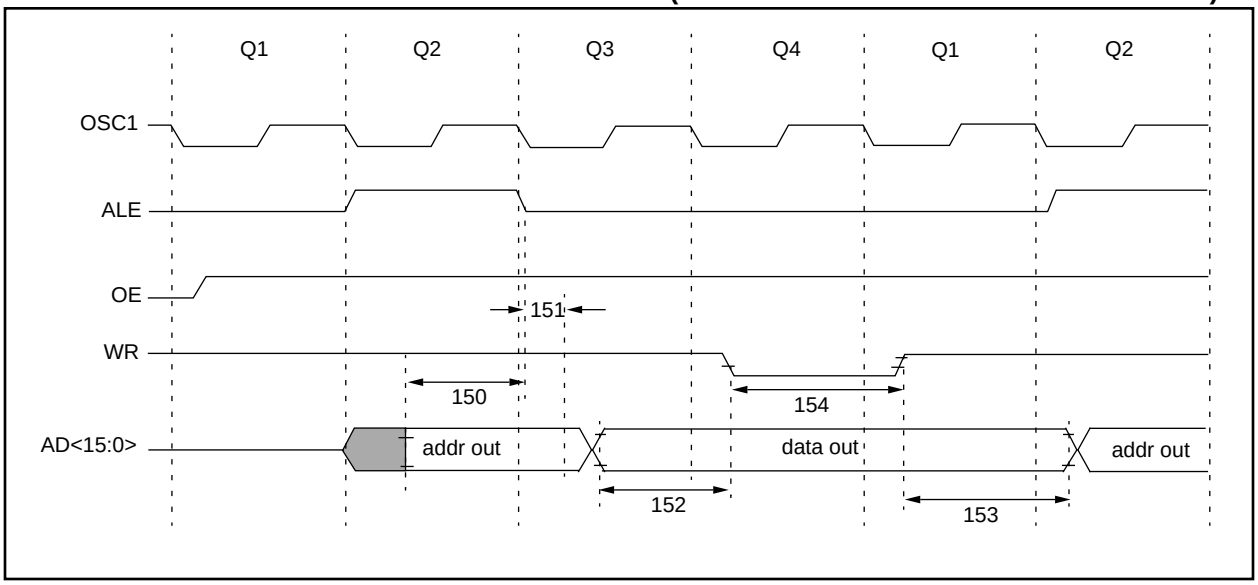


TABLE 19-11: MEMORY INTERFACE WRITE REQUIREMENTS (NOT SUPPORTED IN PIC17LC4X DEVICES)

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
150	TadV2alL	AD<15:0> (address) valid to ALE↓ (address setup time)	0.25Tcy - 10	—	—	ns	
151	TalL2adI	ALE↓ to address out invalid (address hold time)	0	—	—	ns	
152	TadV2wrL	Data out valid to $\overline{WR}$↓ (data setup time)	0.25Tcy - 40	—	—	ns	
153	TwrH2adI	$\overline{WR}$↑ to data out invalid (data hold time)	—	0.25TCY §	—	ns	
154	TwrL	$\overline{WR}$ pulse width	—	0.25TCY §	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-2: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

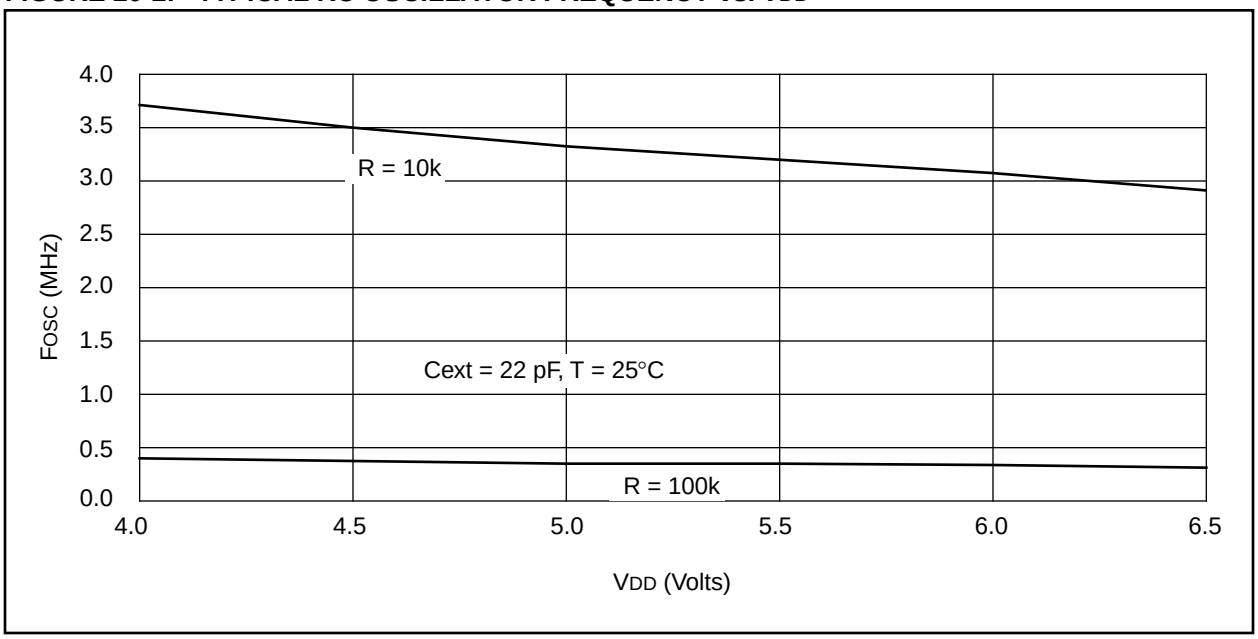
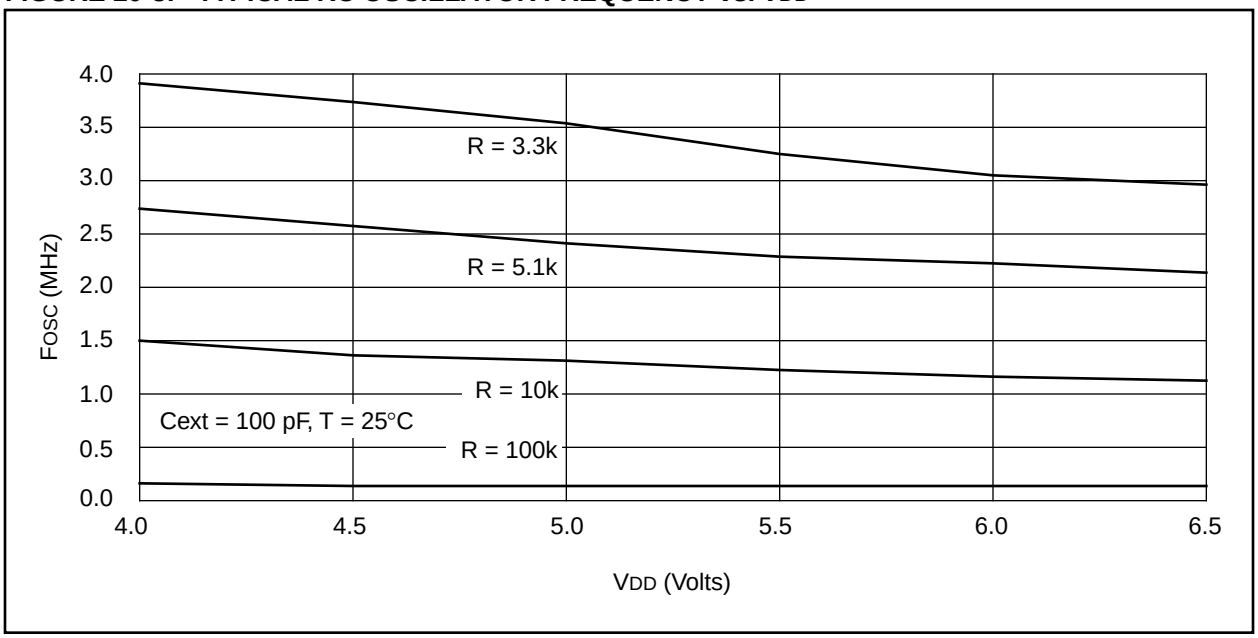
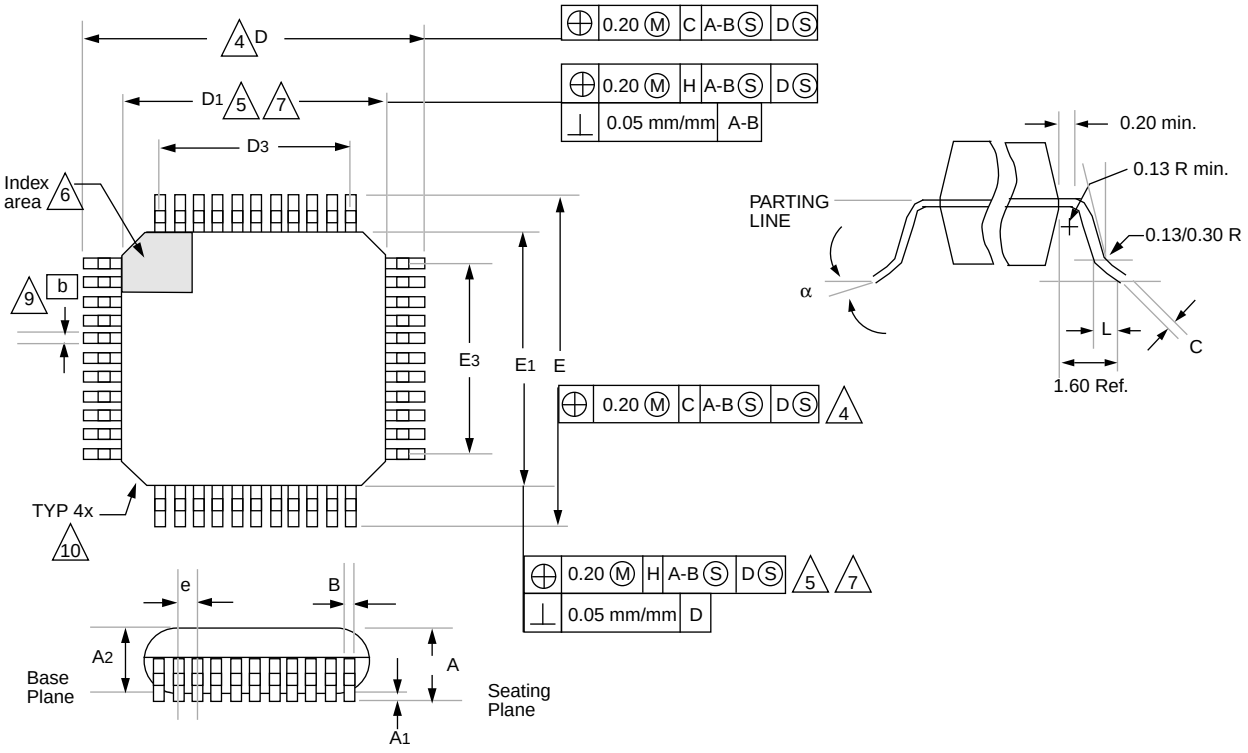


FIGURE 20-3: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD



NOTES:

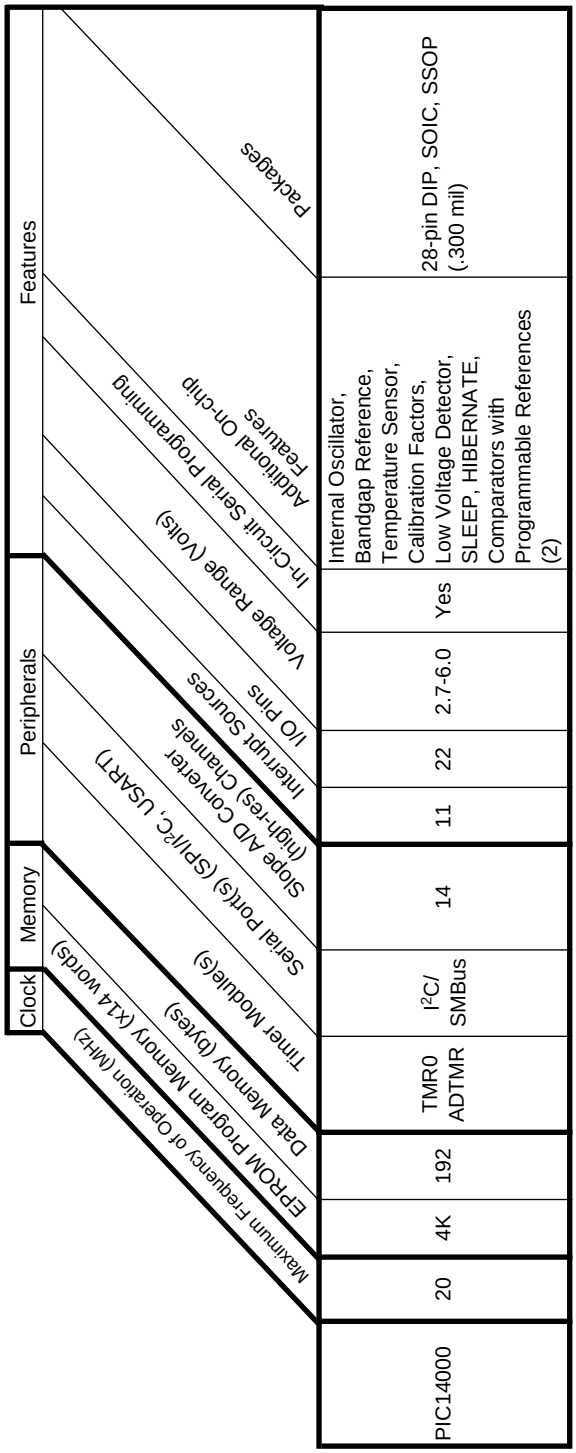
21.4 44-Lead Plastic Surface Mount (MQFP 10x10 mm Body 1.6/0.15 mm Lead Form)



Package Group: Plastic MQFP						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	7°		0°	7°	
A	2.000	2.350		0.078	0.093	
A1	0.050	0.250		0.002	0.010	
A2	1.950	2.100		0.768	0.083	
b	0.300	0.450	**Typical**	0.011	0.018	**Typical**
C	0.150	0.180		0.006	0.007	
D	12.950	13.450		0.510	0.530	
D1	9.900	10.100		0.390	0.398	
D3	8.000	8.000	**Reference**	0.315	0.315	**Reference**
E	12.950	13.450		0.510	0.530	
E1	9.900	10.100		0.390	0.398	
E3	8.000	8.000	**Reference**	0.315	0.315	**Reference**
e	0.800	0.800		0.031	0.032	
L	0.730	1.030		0.028	0.041	
N	44	44		44	44	
CP	0.102	–		0.004	–	

APPENDIX E: PIC16/17 MICROCONTROLLERS

E.1 PIC14000 Devices



E.6 PIC16C8X Family of Devices

	Clock	Memory				Peripherals		Features		
	Maximum Frequency of Operation (MHz)	Program Memory	Flash	EEPROM	ROM	Data Memory (bytes)	Data EEPROM (bytes)	Timer Module(s)	Interrupt Sources	I/O Pins	Voltage Range (Volts)	Packages
PIC16C84	10	—	1K	—	36	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16F84(1)	10	1K	—	—	68	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16CR84(1)	10	—	—	1K	68	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16F83(1)	10	512	—	—	36	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16CR83(1)	10	—	—	512	36	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC

All PIC16/17 family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect, and high I/O current capability.

All PIC16C8X family devices use serial programming with clock pin RB6 and data pin RB7.

Note 1: Please contact your local sales office for availability of these devices.

APPENDIX F: ERRATA FOR PIC17C42 SILICON

The PIC17C42 devices that you have received have the following anomalies. At present there is no intention for future revisions to the present PIC17C42 silicon. If these cause issues for the application, it is recommended that you select the PIC17C42A device.

Note:	New designs should use the PIC17C42A.

1. When the Oscillator Start-Up Timer (OST) is enabled (in LF or XT oscillator modes), any interrupt that wakes the processor may cause a WDT reset. This occurs when the WDT is greater than or equal to 50% time-out period when the SLEEP instruction is executed. This will not occur in either the EC or RC oscillator modes.

   Work-arounds

a) Always ensure that the CLRWDT instruction is executed before the WDT increments past 50% of the WDT period. This will keep the “false” WDT reset from occurring.
b) When using the WDT as a normal timer (WDT disabled), ensure that the WDT is less than or equal to 50% time-out period when the SLEEP instruction is executed. This can be done by monitoring the $\overline{TO}$ bit for changing state from set to clear. Example 1 shows putting the PIC17C42 to sleep.

EXAMPLE F-1: PIC17C42 TO SLEEP

```
      BTFSS   CPUSTA, TO  ; TO = 0?
      CLRWDT              ; YES, WDT = 0
LOOP  BTFSC   CPUSTA, TO  ; WDT rollover?
      GOTO    LOOP        ; NO, Wait
      SLEEP               ; YES, goto Sleep
```

2. When the clock source of Timer1 or Timer2 is selected to external clock, the overflow interrupt flag will be set twice, once when the timer equals the period, and again when the timer value is reset to 0h. If the latency to clear TMRxIF is greater than the time to the next clock pulse, no problems will be noticed. If the latency is less than the time to the next timer clock pulse, the interrupt will be serviced twice.

   Work-arounds

a) Ensure that the timer has rolled over to 0h before clearing the flag bit.
b) Clear the timer in software. Clearing the timer in software causes the period to be one count less than expected.

Design considerations

The device must not be operated outside of the specified voltage range. An external reset circuit must be used to ensure the device is in reset when a brown-out occurs or the V_{DD} rise time is too long. Failure to ensure that the device is in reset when device voltage is out of specification may cause the device to lock-up and ignore the $\overline{MCLR}$ pin.

E

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LIST OF EQUATIONS

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